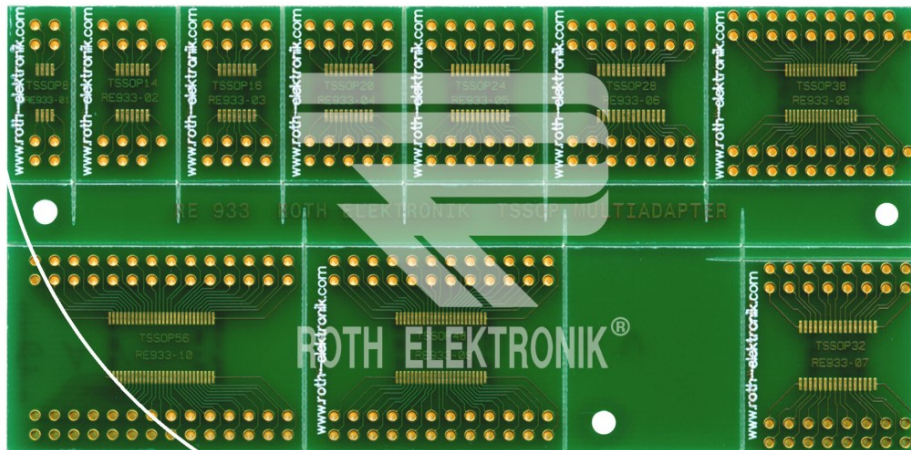


TSSOP-SMD Multiadapter (thin shrink small outline package)



RE933

- FR4 EPOXY fibre-glass 1.50 mm double-sided 35 µm CU (pth)
- Solder and component side with chem. NI/AU surface and solder stop mask
- hole dia 1.00 mm
- adapter for 10 different TSSOP
- pitch 0.65 mm / 0.50 mm
- pre-scratched rated break point for the separation of individual modules from the board
- size 58.90 x 120.10 mm

Modul-No	Pitch	mil	Pin/Quantity	Size (mm)
RE933-01	0.65	22.5	8	4.4 (173 mil)
RE933-02	0.65	22.5	14	4.4 (173 mil)
RE933-03	0.65	22.5	16	4.4 (173 mil)
RE933-04	0.65	22.5	20	4.4 (173 mil)
RE933-05	0.65	22.5	24	4.4 (173 mil)
RE933-06	0.65	22.5	28	4.4 (173 mil)
RE933-07	0.65	22.5	32	6.1 (240 mil)
RE933-08	0.50	19.6	38	4.4 (173 mil)
RE933-09	0.50	19.6	48	6.1 (240 mil)
RE933-10	0.50	19.6	56	6.1 (240 mil)